

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3802604

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	BYUNG TAI DO	03/22/2016
	ARNEL SENOSA TRASPORTO	03/22/2016
RECEIVING PARTY DATA		
Name:	STATS CHIPPAAC, LTD.	
Street Address:	10 ANG MO KIO STREET 65	
Internal Address:	TECHPOINT #04-08/09	
City:	SINGAPORE	
State/Country:	SINGAPORE	
Postal Code:	569059	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	15082190	
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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Correspondent Name:	PATENT LAW GROUP: ATKINS AND ASSOCIATES	
Address Line 1:	55 N. ARIZONA PLACE	
Address Line 2:	SUITE 104	
Address Line 4:	CHANDLER, ARIZONA 85225	
ATTORNEY DOCKET NUMBER:	2515.0486	
NAME OF SUBMITTER:	LISA ROSSETTI	
SIGNATURE:	/Lisa Rossetti/	
DATE SIGNED:	03/28/2016	
Total Attachments: 2		
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source=15082190ASSIGNMENT#page2.tif		

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYUNG TAI DO of Singapore, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, Techpoint #04-08/09, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING A PACKAGE IN-FAN OUT PACKAGE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0486, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

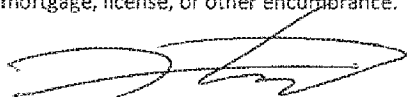
I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

22 Mar 2016
Date Signed


Signature for BYUNG TAI DO

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, ARNEL SENOSA TRASPORTO of Singapore, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 63, Techpoint #04-08/09, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING A PACKAGE IN-FAN OUT PACKAGE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0486, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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22 MAR 2016

Date Signed



Signature for ARNEL SENOSA TRASPORTO